

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040201102"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 11:05
S2	2	"20020043723"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 11:08
S3	2	("6538326").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/02 11:08
S4	1	"5597737".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S5	1	"6229221".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S6	1	"6127715".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S7	1	"5989991".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S8	1	"5597737".PN.	USPAT; USOCR	OR	ON	2005/06/02 11:13
S9	6838	@ad<="20040408" and (257/758). ccls. or (257/759).ccls. or (257/780).ccls. or (257/784).ccls. or (257/E23.151).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:36
S10	33	@ad<="20040408" and 'bonding pad' and 'first wire' and 'second wire' and 'semiconductor element'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:00
S11	2	("5989991").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/02 11:59
S13	1369	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor' with 'structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:02
S15	682	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor' with 'structure' and 'wiring'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:02

S16	298	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor device' and 'wiring layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:22
S17	1	"6399997".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:12
S18	1	"6392300".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:12
S19	1	"6303459".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:13
S20	1	"6291331".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:13
S21	1	"6232662".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:14
S22	1	"6124198".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:14
S23	1	"5554940".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:15
S24	1	"5554940".PN.	USPAT; USOCR	OR	ON	2005/06/02 12:15
S25	30	@ad<="20040408" and 'bonding pad' and 'adhesion' and 'semiconductor device' and 'Multilayer wiring structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:23
S26	693	@ad<="20040408" and (257/459). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:37
S28	2360	@ad<="20040408" and (438/612). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:39
S29	1963	@ad<="20040408" and (438/614). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:39
S30	1063	@ad<="20040408" and (438/618). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 12:39